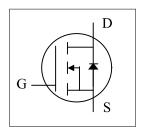


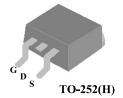
- **▼** Capable of 2.5V Gate Drive
- ▼ Small Size & Ultra\_Low R<sub>DS(ON)</sub>
- **▼** RoHS Compliant & Halogen-Free



BV <sub>DSS</sub>	20V
R <sub>DS(ON)</sub>	4.8m $\Omega$
$I_D^3$	60A

# **Description**

AP2055K series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.



# Absolute Maximum Ratings@T<sub>j</sub>=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	٧
$V_{GS}$	Gate-Source Voltage	<u>+</u> 12	٧
I <sub>D</sub> @T <sub>A</sub> =25°C	Drain Current, V <sub>GS</sub> @ 4.5V <sup>3</sup>	60	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Drain Current, V <sub>GS</sub> @ 4.5V <sup>3</sup>	40	А
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup>	180	Α
EAS	Single pulse avalanche energy	190	mJ
P <sub>D</sub> @T <sub>A</sub> =25°℃	Total Power Dissipation	3.13	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}\!\mathbb{C}$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}\!\mathbb{C}$

#### **Thermal Data**

Symbol	Parameter	Value	Unit
Rthj-c	Maximum Thermal Resistance, Junction-case	5	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	40	°C/W

# Electrical Characteristics@T<sub>j</sub>=25°C(unless otherwise specified)

	<u> </u>	<u> </u>				
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	-	-	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	4.8	5.5	$\mathbf{m}\Omega$
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =12A	-	-	7	$\mathbf{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =1mA	0.5	-	0.9	V
g <sub>fs</sub>	Forward Transconductance	$V_{DS}$ =5V, $I_D$ =20A	-	30	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =16V, V <sub>GS</sub> =0V	-	-	10	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> = <u>+</u> 12V, V <sub>DS</sub> =0V	-	-	<u>+</u> 100	nA
$Q_g$	Total Gate Charge	I <sub>D</sub> =20A	-	32	59.2	nC
$Q_{gs}$	Gate-Source Charge	V <sub>DS</sub> =10V	-	6	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =4.5V	_	6.5	-	nC
$t_{d(on)}$	Turn-on Delay Time	V <sub>DS</sub> =10V	-	10	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =1A	-	18	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega$	_	30	-	ns
t <sub>f</sub>	Fall Time	V <sub>GS</sub> =5V	_	18	_	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	2200	4400	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =10V	-	500	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	200	-	pF
$R_g$	Gate Resistance	f=1.0MHz	-	1.4	2.8	Ω

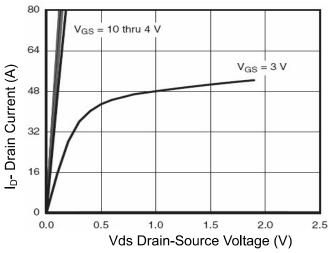
## **Source-Drain Diode**

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =2.5A, V <sub>GS</sub> =0V	1	ı	1.2	٧
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =20A, V <sub>GS</sub> =0V,	-	30	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl/dt=100A/µs	-	26	-	nC

#### Notes:

- 1. Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in<sup>2</sup> 2oz copper pad of FR4 board, t ≤10sec; 135°C/W when mounted on min. copper pad.
- 4. Maximum current limited by package.

## Typical Electrical and Thermal Characteristics (Curves)



**Figure 1 Output Characteristics** 

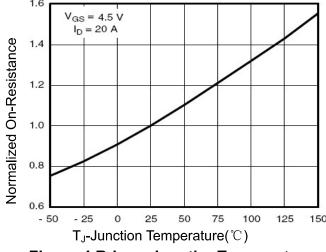
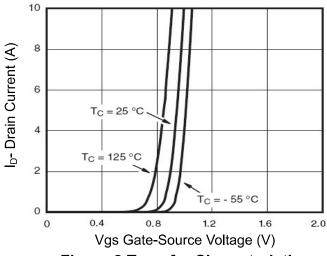


Figure 4 Rdson-JunctionTemperature



**Figure 2 Transfer Characteristics** 

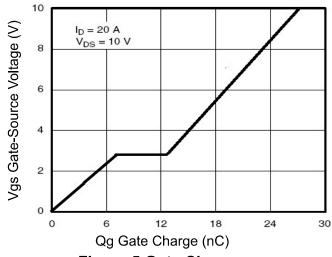


Figure 5 Gate Charge

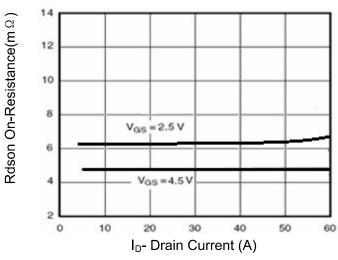


Figure 3 Rdson-Drain Current

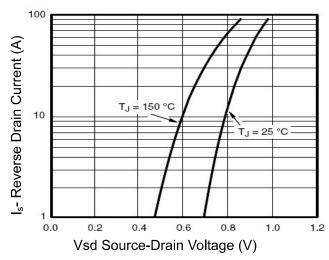
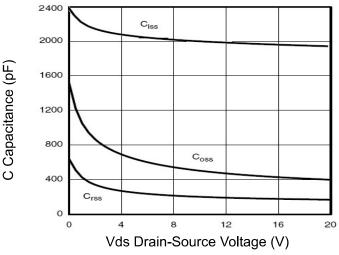


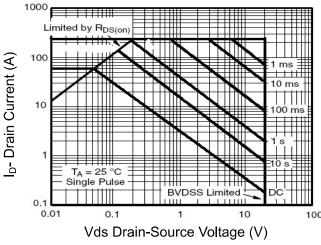
Figure 6 Source- Drain Diode Forward



60 50 40 40 30 20 0 25 50 75 100 125 150 T<sub>J</sub>-Junction Temperature (°C)

Figure 7 Capacitance vs Vds

Figure 9 Power De-rating



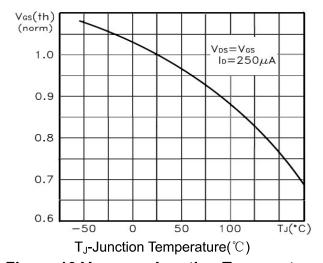


Figure 8 Safe Operation Area

Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

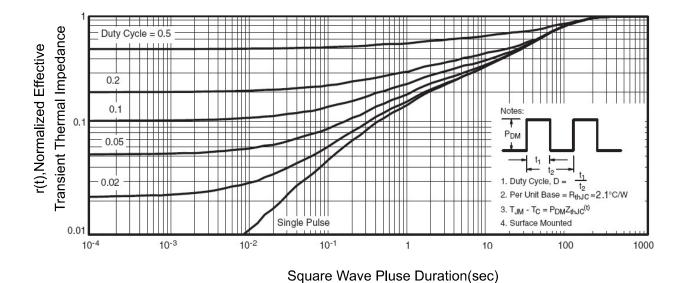
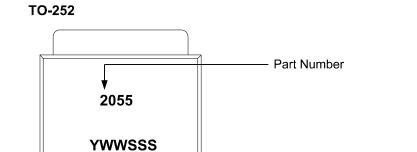


Figure 11 Normalized Maximum Transient Thermal Impedance

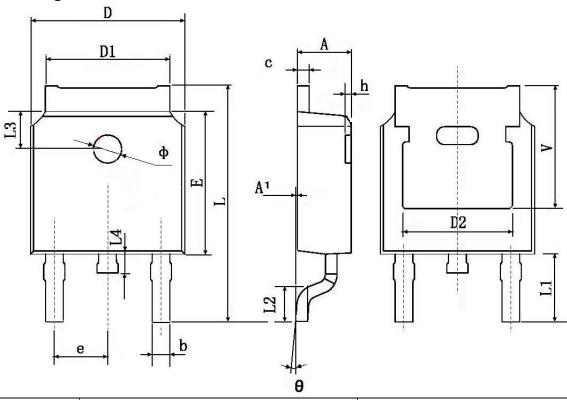


Date Code (YWWSSS)
Y: Last Digit Of The Year

WW: Week SSS: Sequence



# **TO-252 Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830 TYP.		4.830 TYP. 0.190 TYP		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.90	0 TYP.	0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.60	1.600 TYP.		TYP.	
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.35	0 TYP.	0.211 TYP.		